

Title (en)

Terminal crimping quality decision method/device

Title (de)

Anordnung und Verfahren zur Prüfung der Crimpqualität von Kontakten

Title (fr)

Dispositif et procédé d'essai de la qualité de sertissage des bornes

Publication

**EP 1071174 A3 20010829 (EN)**

Application

**EP 00115750 A 20000721**

Priority

JP 20873899 A 19990723

Abstract (en)

[origin: EP1071174A2] The terminal crimping quality decision method/device determines the crimping quality of a terminal crimped to a conductor of an electrical cable by a terminal crimping apparatus. The method uses an envelop of characteristic values obtained when the terminal is crimped to the conductor. The characteristic values are obtained by sensing the deflection of a construction member constituting the terminal crimping apparatus and deflected by a reaction force caused by the crimping. <IMAGE>

IPC 1-7

**H01R 43/048**

IPC 8 full level

**H01R 43/048** (2006.01)

CPC (source: EP)

**H01R 43/0486** (2013.01)

Citation (search report)

- [XA] EP 0500217 A2 19920826 - AMP INC [US]
- [X] DE 4408499 A1 19950921 - ENGBERTS UWE [DE]

Cited by

EP3644461A1; CN102801077A; CN103673965A; EP2173015A1; EP2418737A4; US9331447B2; WO2012078180A3; US8746026B2; US9065190B2

Designated contracting state (EPC)

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DOCDB simple family (publication)

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